TOSHIBA

2SK3075

TOSHIBA FIELD EFFECT TRANSISTOR SILICON N CHANNEL MOS TYPE

2 S K 3 0 7 5

RF POWER MOSFET

FOR VHF- AND UHF-BAND POWER AMPLIFIER

: $P_0 \ge 7.5W$ Output Power

: Gp≥11.7dB Power Gain

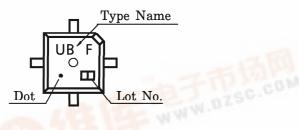
 $: \eta_{\mathbf{D}} \geq 50\%$ Drain Efficiency

MAXIMUM RATINGS (Ta = 25°C)									
CHARACTERISTIC	SYMBOL	RATING	UNIT						
Drain-Source Voltage	$v_{ m DSS}$	30	V						
Gate-Source Voltage	v_{GSS}	25	V						
Drain Current	$I_{\mathbf{D}}$	5	A						
Drain Power Dissipation	P_{D}^*	20	W						
Channel Temperature	$\mathrm{T_{ch}}$	150	°C						
Storage Temperature Range	$\mathrm{T_{stg}}$	-45~150	°C						

*: Tc=25°C When mounted on a 1.6mm glass epoxy PCB

	Unit in mm					
	\$\frac{\phi_{1.2\pmu}}{0.6\pmu}\frac{\phi_{1.2\pmu}}{0.6\pmu}\frac{\phi_{1.2\pmu}}{0.6\pmu}\frac{\phi_{1.2\pmu}}{0.6\pmu}\frac{\phi_{1.2\pmu}}{0.6\pmu}\frac{\phi_{1.2\pmu}}{0.6\pmu}\frac{\phi_{1.2\pmu}}{0.6\pmu}\frac{\phi_{1.2\pmu}}{0.35\pmu}					
	1. GATE 2. SOURCE (HEAT SINK) 3. DRAIN					
1	JEDEC —					
_	EIAJ —					
	TOSHIBA 2-5N1A					

MARKING



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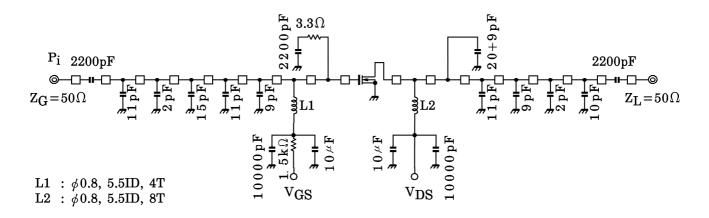
ELECTRICAL CHARACTERISTICS (Ta = 25°C)

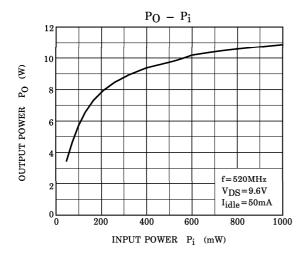
CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Output Power	PO	$\begin{aligned} &V_{DS}\!=\!9.6V\\ &\text{Iidle}\!=\!50\text{mA}\left(V_{GS}\!=\!\text{adjust}\right)\\ &f\!=\!520\text{MHz},P_{i}\!=\!500\text{mW}\\ &Z_{G}\!=\!Z_{L}\!=\!50\Omega\end{aligned}$	7.5	_	_	W
Drain Efficiency	$\eta_{\mathbf{D}}$		50	_	_	%
Power Gain	$G_{\mathbf{P}}$		11.7	_	_	dB
Gate Threshold Voltage	$ m V_{th}$	$V_{DS} = 9.6V, I_{D} = 0.5mA$	1.0	1.5	2.0	V
Drain Cut-off Current	$I_{ m DSS}$	$V_{DS}=20V, V_{GS}=0$	_	_	10	μ A
Gate-Source Leakage Current	IGSS	$V_{GS}=10V, V_{DS}=0$		ı	5	μ A

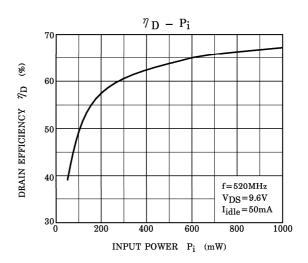
HANDLING PRECAUTION

• When handling individual devices, be sure that working desks, human bodies and soldering iron are protected against electrostatic electricity.

RF OUTPUT POWER TEST FIXTURE







CAUTION

These are only typical curves and devices are not necessarily guaranteed at these curves.